



CALL FOR PAPERS MIXDES 2020

27th International Conference
Mixed Design of Integrated
Circuits and Systems

Wrocław, Poland, June 25-27, 2020
<http://www.mixdes.org>



Organised by:

Department of Microelectronics and Computer Science,
Lodz University of Technology, Poland
Institute of Microelectronics and Optoelectronics,
Warsaw University of Technology, Poland

in co-operation with:

Poland Section IEEE - ED & CAS Chapters

Section of Microelectronics and Section of Signals, Electronic Circuits and Systems
of the Committee of Electronics and Telecommunication of the Polish Academy of Sciences

Commission of Electronics and Photonics of Polish National Committee of International Union of Radio Science

GENERAL INVITED PAPERS

Maximizing the Efficiency of CMOS Front-illuminated Solar cell for Self-powered IoT Sensor Applications

Poki Chen (National Taiwan University of Science and Technology, Taiwan)

Miniaturized Sensors for Planetary Applications

Mina Rais-Zadeh (NASA Jet Propulsion Laboratory, California Institute of Technology, USA)

Semiconducting Oxide Electronics for Newly Emerging Applications

Arokia Nathan (University of Cambridge, UK)

Sensor Design Made by Bosch

Mike Schwarz (Robert Bosch GmbH, Germany)

PAPER SUBMISSION

Full papers should be submitted to the Organising Committee only in electronic form (MS Word, OpenOffice Writer, Rich Text Format, LaTeX or PDF document). The required format is available on the Conference Web page. Authors are asked to indicate the topic into which their papers fall. Papers presented at the conference will be printed in the proceedings directly from the files submitted by the authors.

Deadline for receipt of papers: February 29th, 2020

REGULAR SESSIONS

<i>Design of Integrated Circuits and Microsystems</i>	Design methodologies. Digital and analogue synthesis. Hardware-software codesign. Reconfigurable hardware. Hardware description languages. Intellectual property-based design. Design reuse.
<i>Thermal Issues in Microelectronics</i>	Thermal and electro-thermal modelling, simulation methods and tools. Thermal mapping. Thermal protection circuits.
<i>Analysis and Modelling of ICs and Microsystems</i>	Simulation methods and algorithms. Behavioural modelling with VHDL-AMS and other advanced modelling languages. Microsystems modelling. Model reduction. Parameter identification.
<i>Microelectronics Technology and Packaging Testing and Reliability</i>	New microelectronic technologies. Packaging. Sensors and actuators. Design for testability and manufacturability. Measurement instruments and techniques.
<i>Power Electronics</i>	Design, manufacturing and simulation of power semiconductor devices. Hybrid and monolithic Smart Power circuits. Power integration. Wide band gap devices.
<i>Signal Processing</i>	Digital and analogue filters, telecommunication circuits. Neural networks. Artificial intelligence. Fuzzy logic. Low voltage and low power solutions.
<i>Embedded Systems</i>	Design, verification and applications.
<i>Medical Applications</i>	Medical and biotechnology applications. Thermography in medicine.

SPECIAL SESSIONS

Compact Modeling Support for Micro and Nanoelectronic System Development

organised by Dr. Daniel Tomaszewski (Institute of Electron Technology, Poland)
and Dr. Władysław Grabiński (GMC Suisse, Switzerland)

Large Scale Research Facilities

organised by Prof. A. Napieralski
and Dr. Wojciech Cichalewski (Lodz University of Technology, Poland)

Offshore Wind Farm Energy & Power Cables

Design aspects of submarine power cables
Cable technologies for wind farm offshore applications
Installation, operation and maintenance of submarine power cables
Modern testing technologies for export- and inter-array cables
organised by Prof. E. Gulski (onsite hv solutions ag, Switzerland)
and Prof. G. Anders (Lodz University of Technology, Poland)

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